



HMPSA64

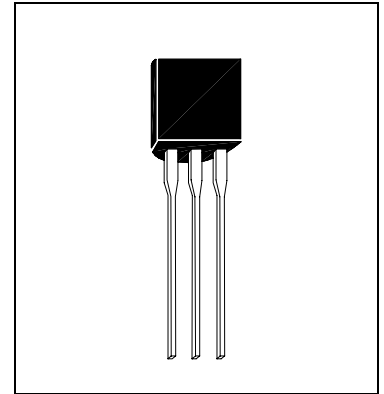
PNP SILICON TRANSISTOR

Description

The HMPSA64 is designed for application requiring extremely high current gain at collector currents to 500mA.

Features

- High D.C Current Gain
- For Complementary Use with NPN Type HMPSA14



Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage -30 V
VCEO Collector to Emitter Voltage -30 V
VEBO Emitter to Base Voltage -10 V
IC Collector Current -500 mA

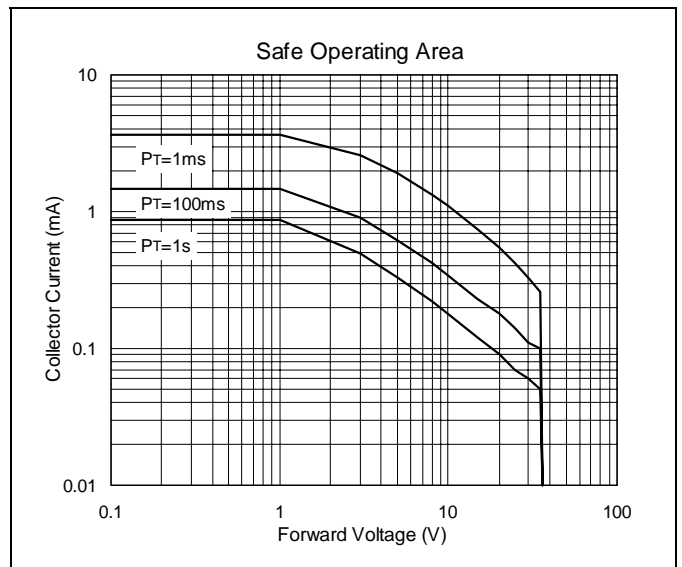
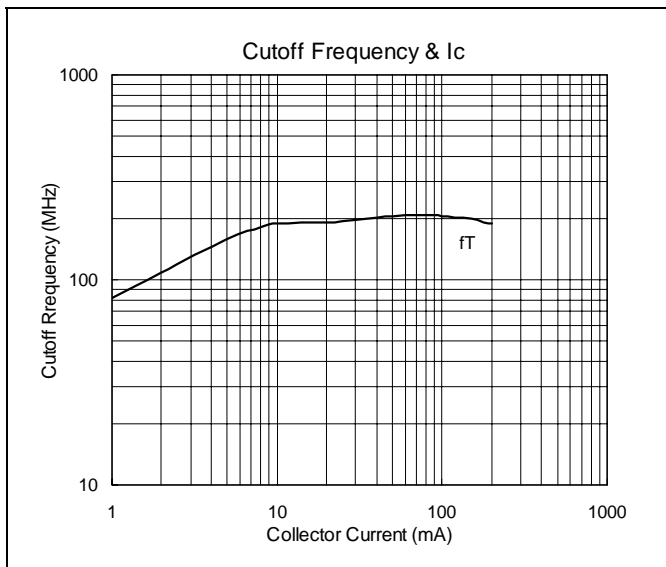
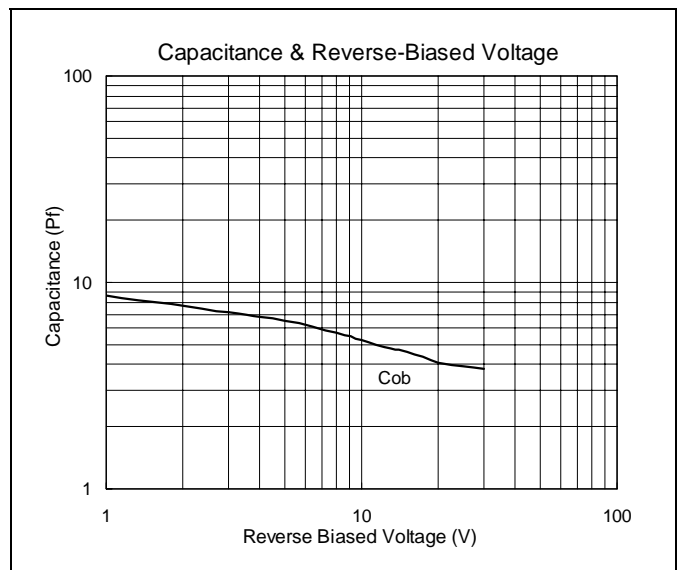
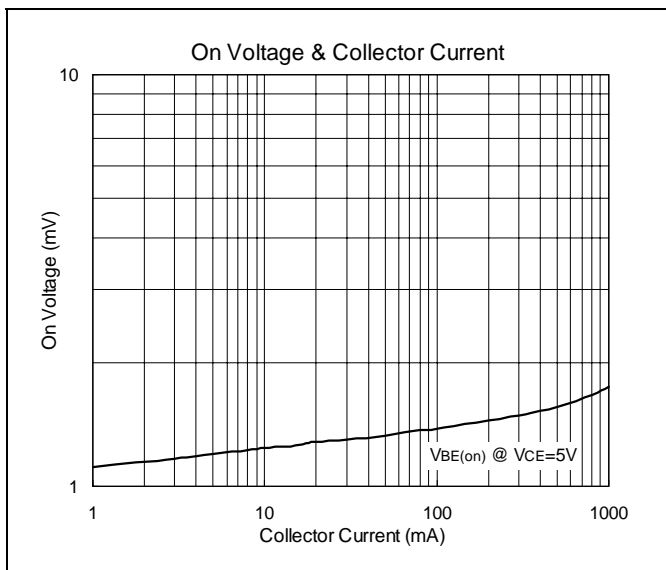
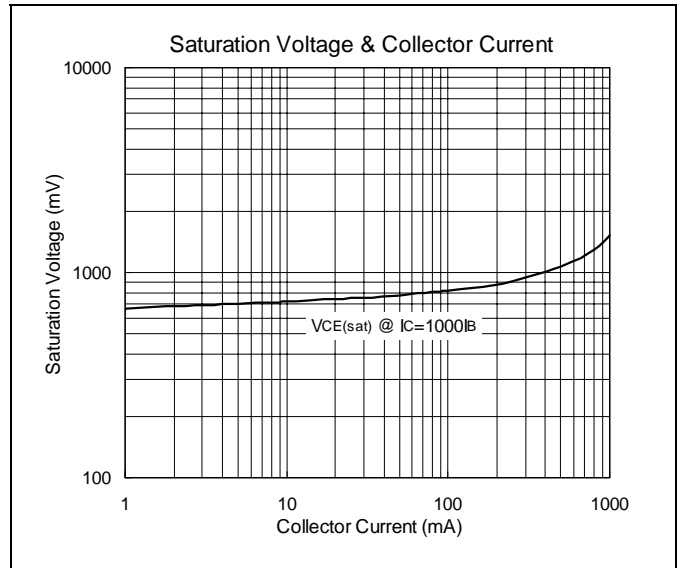
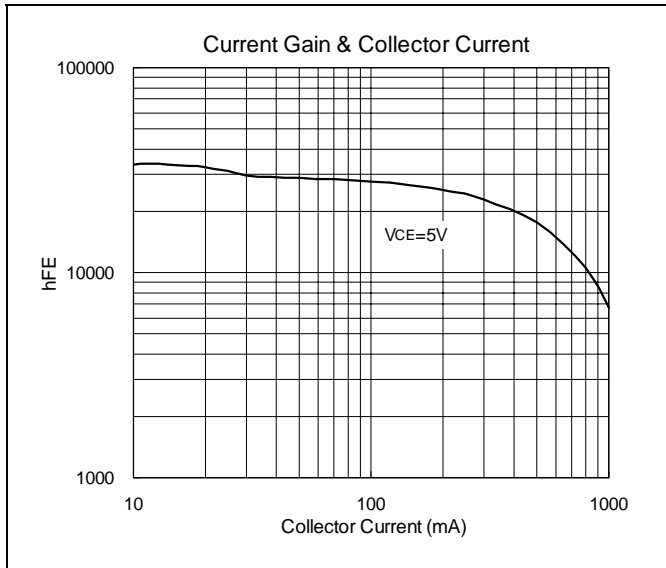
Characteristics (Ta=25°C)

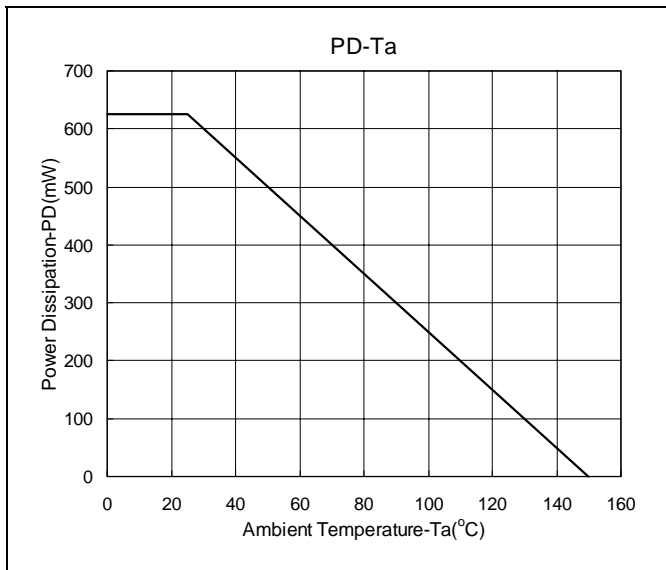
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-30	-	-	V	IC=-100uA, IE=0
BVCES	-30	-	-	V	IC=-100uA, IB=0
BVEBO	-10	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-100	nA	VCB=-30V, IE=0
IEBO	-	-	-100	nA	VEB=-10V, IC=0
*VCE(sat)	-	-	-1.5	V	IC=-100mA, IB=-0.1mA
VBE(on)	-	-	-2	V	IC=-100mA, VCE=-5V
*hFE1	10	-	-	K	IC=-10mA, VCE=-5V
*hFE2	20	-	-	K	IC=-100mA, VCE=-5V
fT	125	-	-	pF	IC=-100mA, VCE=-5V, f=100MHZ

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



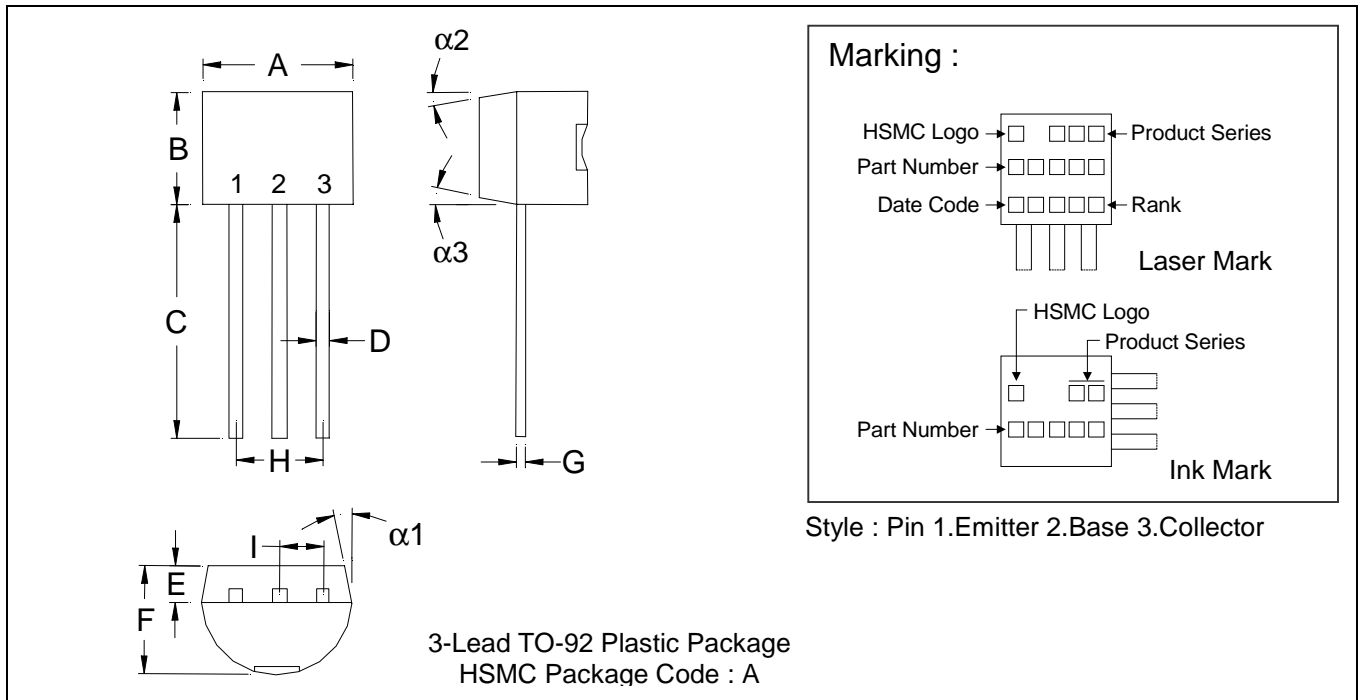
Characteristics Curve







TO-92 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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